Integrated
Circuit
Systems, Inc.

ICS853011

LOW SKEW, 1-TO-2 DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

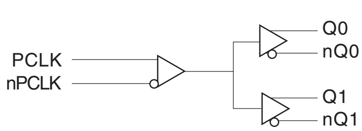
GENERAL DESCRIPTION

The ICS853011 is a low skew, high performance 1-to-2 Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS853011 is characterized to operate from either a 2.5V or a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS853011 ideal for those clock distribution applications demanding well defined performance and repeatability.

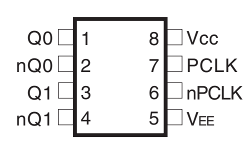
FEATURES

- 2 differential 2.5V/3.3V LVPECL / ECL outputs
- 1 differential PCLK, nPCLK input pair
- PCLK, nPCLK pair can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Maximum output frequency: >3GHz
- Translates any single ended input signal to 3.3V LVPECL levels with resistor bias on nPCLK input
- Output skew: 5ps (typical)
- Part-to-part skew: 130ps (maximum)
- Propagation delay: 390ps (maximum)
- Additive phase jitter, RMS: 0.06ps (typical)
- LVPECL mode operating voltage supply range: V_{CC} = 2.375V to 3.8V, V_{EE} = 0V
- ECL mode operating voltage supply range: V_{CC} = 0V, V_{EE} = -3.8V to -2.375V
- -40°C to 85°C ambient operating temperature
- Pin compatible with MC100LVEP11 and SY100EP11U

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS853011
8-Lead SOIC
3.90mm x 4.90mm x 1.37mm package body
M Package
Top View

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 2	Q0, nQ0	Output		Differential output pair. LVPECL interface levels.
3, 4	Q1, nQ1	Output		Differential output pair. LVPECL interface levels.
5	V_{EE}	Power		Negative supply pin.
6	nPCLK	Input	Pullup/ Pulldown	Clock input. $V_{CC}/2$ default when left floating. LVPECL interface levels.
7	PCLK	Input	Pulldown	Clock input. Default LOW when left floating. LVPECL interface levels.
8	V_{CC}	Power		Positive supply pin.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$R_{PULLDOWN}$	Input Pulldown Resistor			75		KΩ
$R_{VCC/2}$	Pullup/Pulldown Resistors			50		KΩ

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC}	4.6V (LVPECL mode, V_{EE} = 0)
Negative Supply Voltage, V_{EE}	-4.6V (ECL mode, V_{CC} = 0)
Inputs, V_I (LVPECL mode)	-0.5V to V_{CC} + 0.5V
Inputs, V_I (ECL mode)	0.5V to V_{EE} - 0.5V
Outputs, I_O	
Continuous Current	50mA
Surge Current	100mA
Operating Temperature Range, TA	-40°C to +85°C
Storage Temperature, T_{STG}	-65°C to 150°C
Package Thermal Impedance, θ_{JA} (Junction-to-Ambient)	112.7°C/W (0 lfpm)

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, V_{CC} = 2.375V TO 3.8V; V_{EE} = 0V

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Positive Supply Voltage		2.375	3.3	3.8	V
I_{EE}	Power Supply Current				25	mA

TABLE 3B. LVPECL DC CHARACTERISTICS, V_{CC} = 3.3V; V_{EE} = 0V

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		2.175	2.275	2.38	2.225	2.295	2.37	2.22	2.295	2.365	V
V_{OL}	Output Low Voltage; NOTE 1		1.405	1.545	1.68	1.425	1.52	1.615	1.44	1.535	1.63	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	V
V_{CMR}	Input High Voltage Common Mode Range; NOTE 2, 3		1.2		3.3	1.2		3.3	1.2		3.3	V
I_{IH}	Input High Current	PCLK, nPCLK			150			150			150	µA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			µA
		nPCLK	-150			-150			-150			µA

Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.925V to -0.5V.
NOTE 1: Outputs terminated with 50Ω to V_{CCO} - 2V.
NOTE 2: Common mode voltage is defined as V_{IH}.
NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is V_{CC} + 0.3V.

TABLE 3C. LVPECL DC CHARACTERISTICS, V_{CC} = 2.5V; V_{EE} = 0V

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		1.375	1.475	1.58	1.425	1.495	1.57	1.42	1.495	1.565	V
V_{OL}	Output Low Voltage; NOTE 1		0.605	0.745	0.88	0.625	0.72	0.815	0.64	0.735	0.83	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	V
V_{CMR}	Input High Voltage Common Mode Range; NOTE 2, 3		1.2		2.5	1.2		2.5	1.2		2.5	V
I_{IH}	Input High Current	PCLK, nPCLK			150			150			150	µA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			µA
		nPCLK	-150			-150			-150			µA

For notes see above Table 3B, 3.3V LVPECL DC Characteristics.

TABLE 3D. ECL DC CHARACTERISTICS, V_{CC} = 0V; V_{EE} = -3.8V TO -2.375V

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output High Voltage; NOTE 1		-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.08	-1.005	-0.935	V
V_{OL}	Output Low Voltage; NOTE 1		-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.765	-1.67	V
V_{PP}	Peak-to-Peak Input Voltage		150	800	1200	150	800	1200	150	800	1200	V
V_{CMR}	Input High Voltage Common Mode Range; NOTE 2, 3		V_{EE}+1.2V		0	V_{EE}+1.2V		0	V_{EE}+1.2V		0	V
I_{IH}	Input High Current	PCLK, nPCLK			150			150			150	µA
I_{IL}	Input Low Current	PCLK	-10			-10			-10			µA
		nPCLK	-150			-150			-150			µA

Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.925V to -0.5V.
NOTE 1: Outputs terminated with 50Ω to V_{CCO} - 2V.
NOTE 2: Common mode voltage is defined as V_{IH}.
NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is V_{CC} + 0.3V.

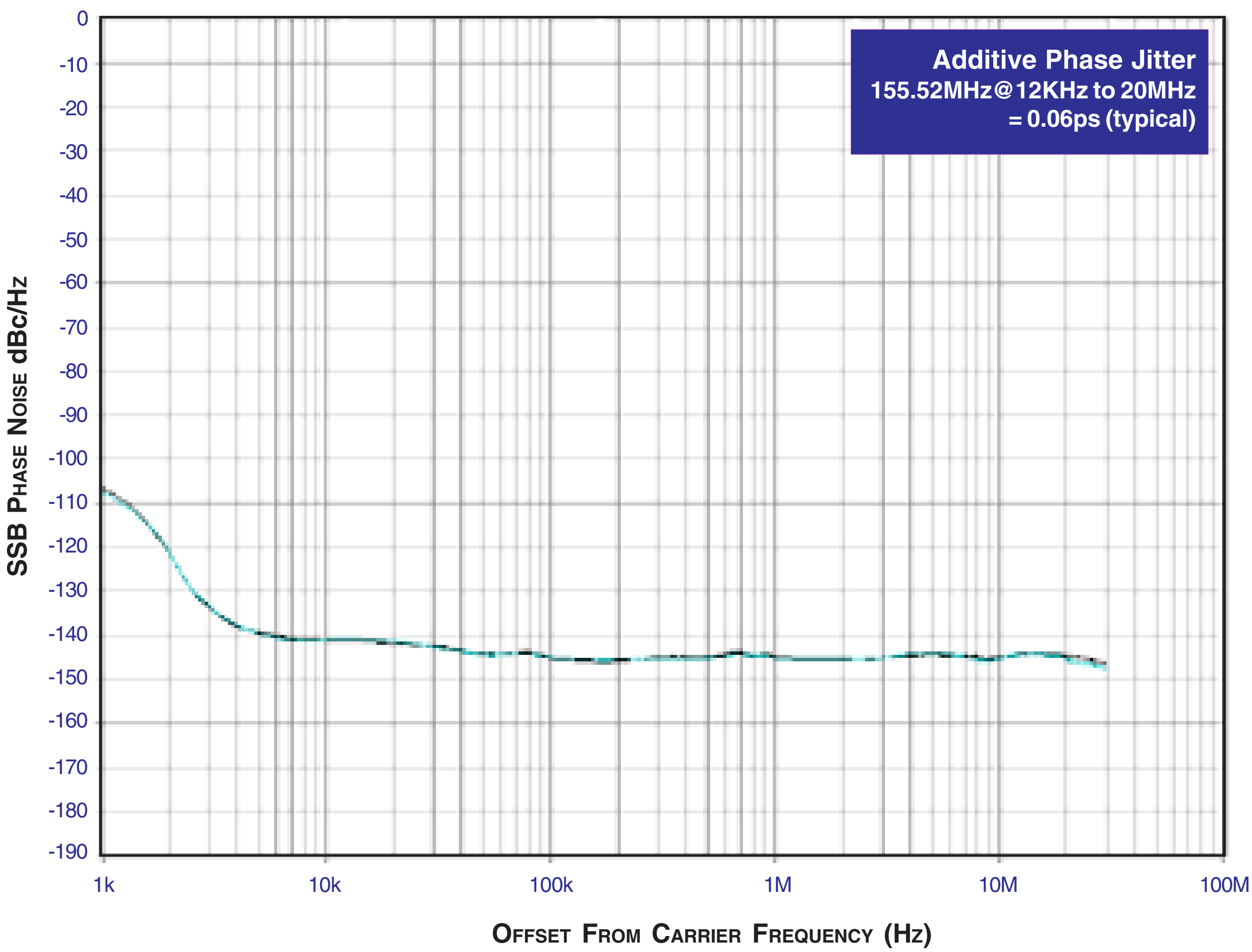
TABLE 4. AC CHARACTERISTICS, V_{CC} = 0V; V_{EE} = -3.8V TO -2.375V OR V_{CC} = 2.375 TO 3.8V; V_{EE} = 0V

Symbol	Parameter		-40°C			25°C			85°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Output Frequency				>3			>3			>3	GHz
t_{PD}	Propagation Delay; NOTE 1		245		375	260		390	275		415	ps
*t*sk(o)	Output Skew; NOTE 2, 4			5	20		5	20		5	20	ps
*t*sk(pp)	Part-to-Part Skew; NOTE 3, 4				130			130			150	ps
*t*jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section, Integration Range: 12KHz to 20MHz			0.06			0.06			0.06		ps
t_R/t_F	Output Rise/Fall Time	20% to 80%	70		250	80		250	100		250	ps
odc	Output Duty Cycle	f ≤ 1GHz	48	50	52	48	50	52	48	50	52	%

All parameters are measured at f ≤ 1.7GHz, unless otherwise noted.
NOTE 1: Measured from the differential input crossing point to the differential output crossing point.
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.
Measured at the output differential cross points.
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

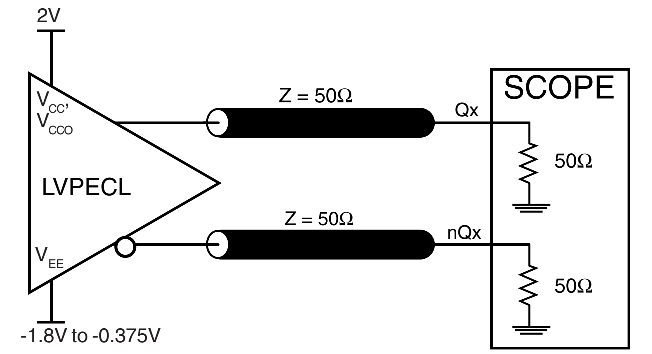
ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise.*** This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.

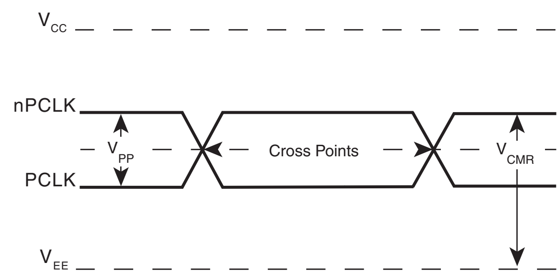


As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.

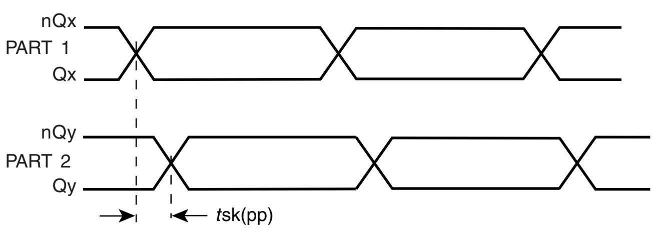
PARAMETER MEASUREMENT INFORMATION



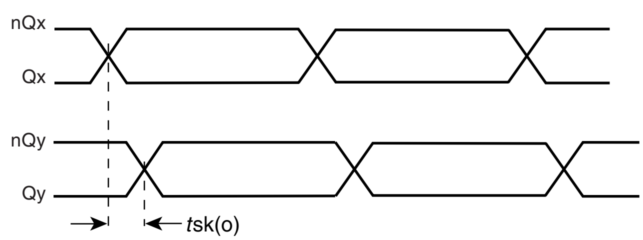
OUTPUT LOAD AC TEST CIRCUIT



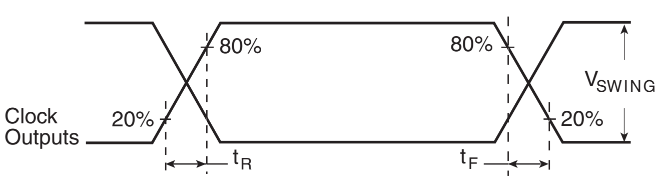
DIFFERENTIAL INPUT LEVEL



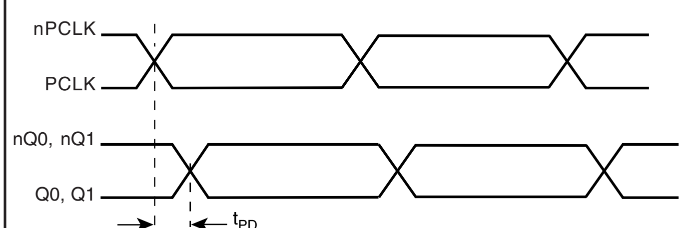
PART-TO-PART SKEW



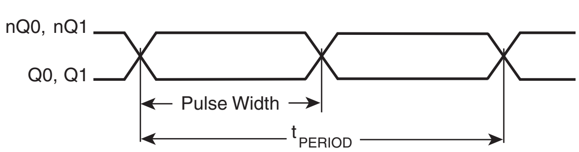
OUTPUT SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



$$odc = \frac{t_{PW}}{t_{PERIOD}}$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage V_REF = $V_{CC}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V_{CC} = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.

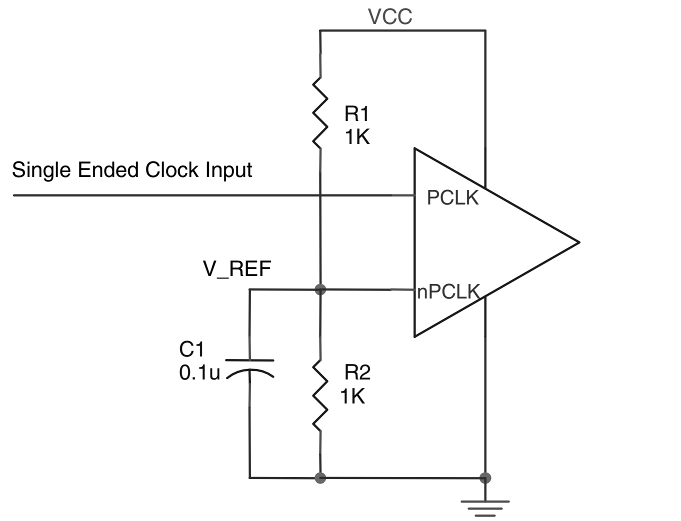
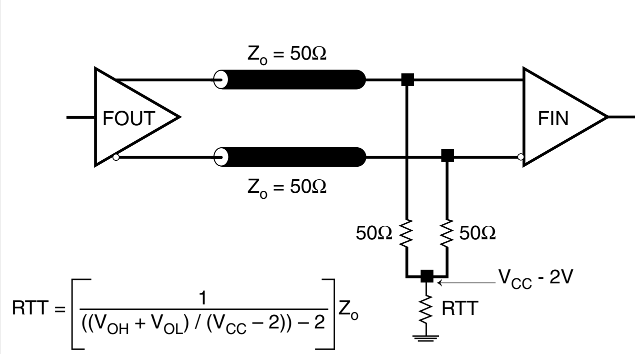


FIGURE 1. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

TERMINATION FOR 3.3V LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 2A and 2B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.



$$RTT = \left[\frac{1}{((V_{OH} + V_{OL}) / (V_{CC} - 2)) - 2}\right] Z_o$$

FIGURE 2A. LVPECL OUTPUT TERMINATION

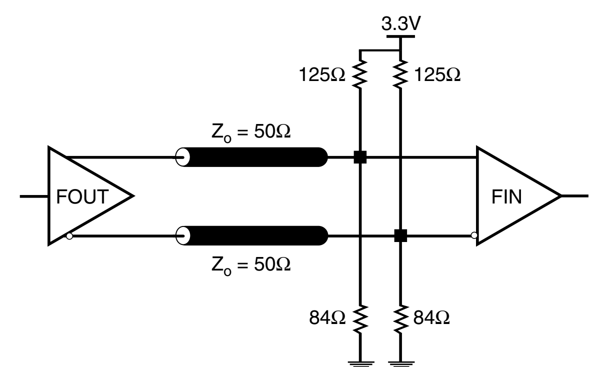


FIGURE 2B. LVPECL OUTPUT TERMINATION

TERMINATION FOR 2.5V LVPECL OUTPUT

Figure 3A and *Figure 3B* show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating 50Ω to V_{CC} - 2V. For V_{CC} = 2.5V, the V_{CC} - 2V is very close to ground level. The R3 in Figure 3B can be eliminated and the termination is shown in *Figure 3C.*

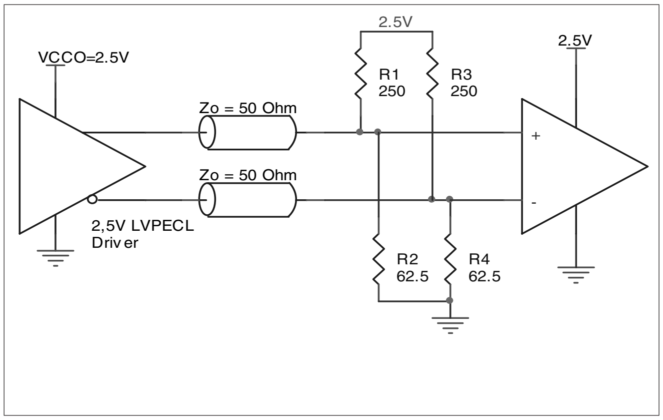


FIGURE 3A. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

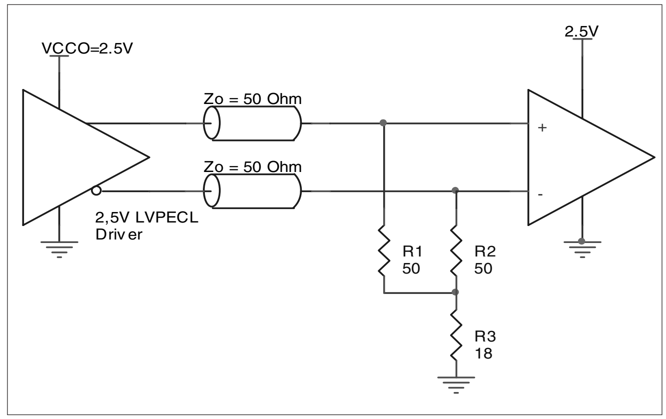


FIGURE 3B. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

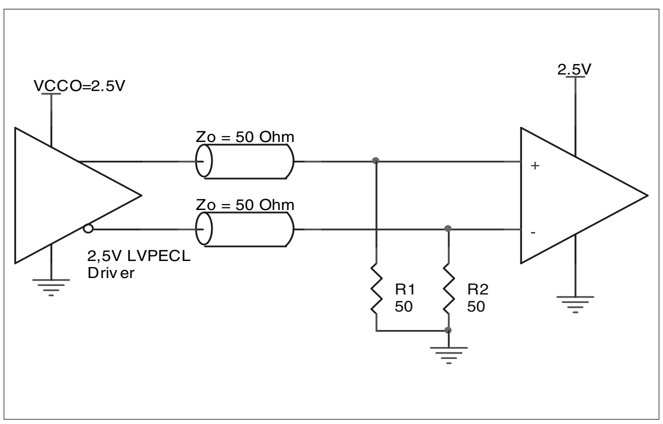


FIGURE 3C. 2.5V LVPECL TERMINATION EXAMPLE

LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. *Figures 4A to 4E* show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

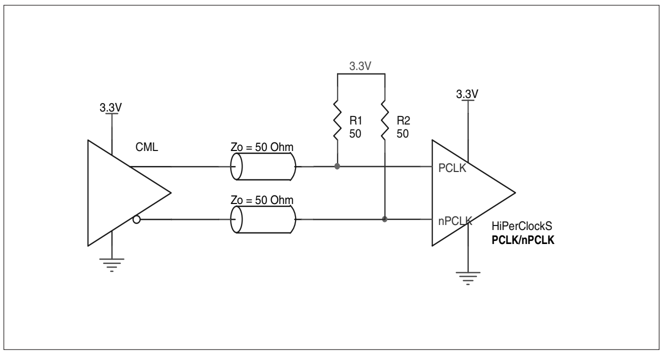


FIGURE 4A. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A CML DRIVER

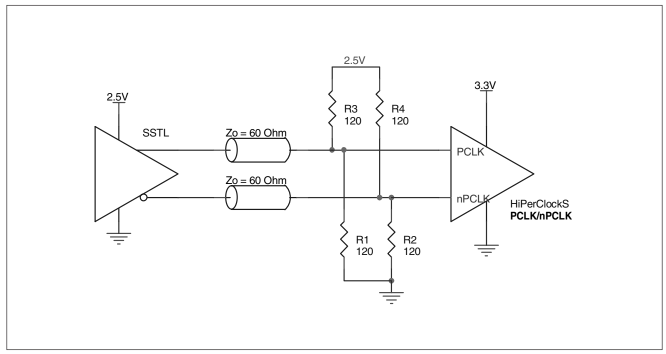


FIGURE 4B. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

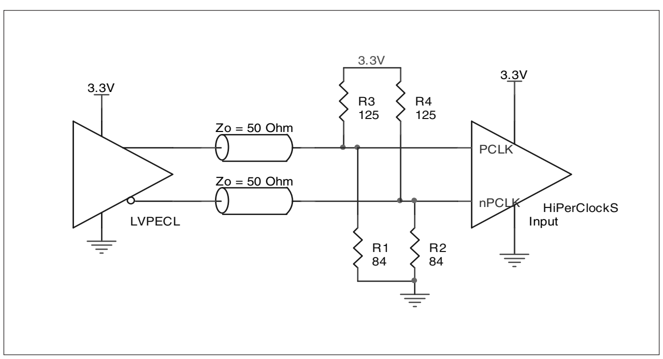


FIGURE 4C. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

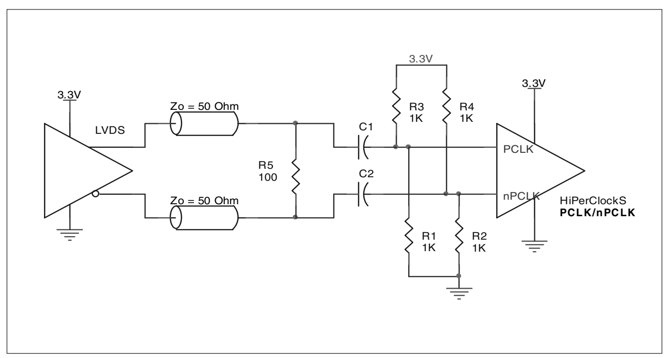


FIGURE 4D. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER

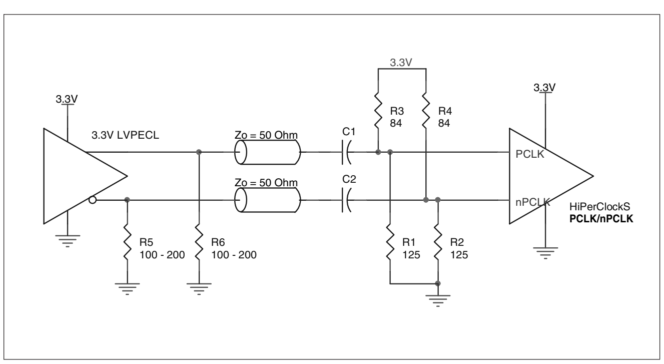


FIGURE 4E. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE

POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS853011.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS853011 is the sum of the core power plus the power dissipated in the load(s).
The following is the power dissipation for V_{CC} = 3.8V, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)$_{MAX}$ = V_{CC_MAX} * I_{EE_MAX} = 3.8V * 25mA = **95mW**
- Power (outputs)$_{MAX}$ = **30.94mW/Loaded Output pair**
  If all outputs are loaded, the total power is 2 * 30.94mW = **61.88mW**

Total Power$_{\_MAX}$ (3.8V, with all outputs switching) = 95mW + 61.88mW = **156.88mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + T_A

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 103.3°C/W per Table 5 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

85°C + 0.157W * 103.3°C/W = 101.2°C. This is well below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 5. THERMAL RESISTANCE θ_{JA} FOR 8-PIN SOIC, FORCED CONVECTION

θ_{JA} by Velocity (Linear Feet per Minute)

	0	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 5.*

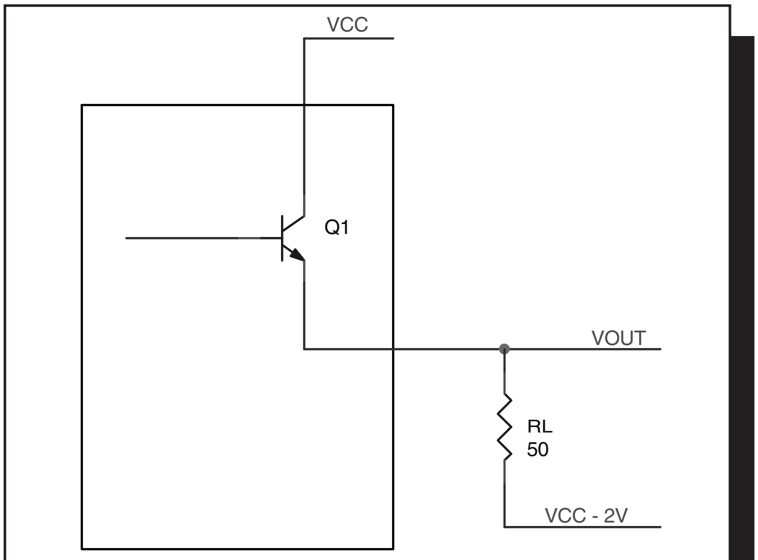


FIGURE 5. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{CC} - 2V.

- For logic high, $V_{OUT} = V_{OH\_MAX} = \mathbf{V_{CC\_MAX}} - \mathbf{0.935V}$

  $(V_{CC\_MAX} - V_{OH\_MAX}) = \mathbf{0.935V}$

- For logic low, $V_{OUT} = V_{OL\_MAX} = \mathbf{V_{CC\_MAX}} - \mathbf{1.67V}$

  $(V_{CC\_MAX} - V_{OL\_MAX}) = \mathbf{1.67V}$

Pd_H is power dissipation when the output drives high.
Pd_L is the power dissipation when the output drives low.

$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) =$
$[(2V - 0.935V)/50\Omega] * 0.935V = \mathbf{19.92mW}$

$Pd\_L = [(V_{OL\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) =$
$[(2V - 1.67V)/50\Omega] * 1.67V = \mathbf{11.02mW}$

Total Power Dissipation per output pair = Pd_H + Pd_L = **30.94mW**

RELIABILITY INFORMATION

TABLE 6. θ_{JA} VS. AIR FLOW TABLE FOR 8 LEAD SOIC

θ_{JA} by Velocity (Linear Feet per Minute)

	0	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS853011 is: 96

PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

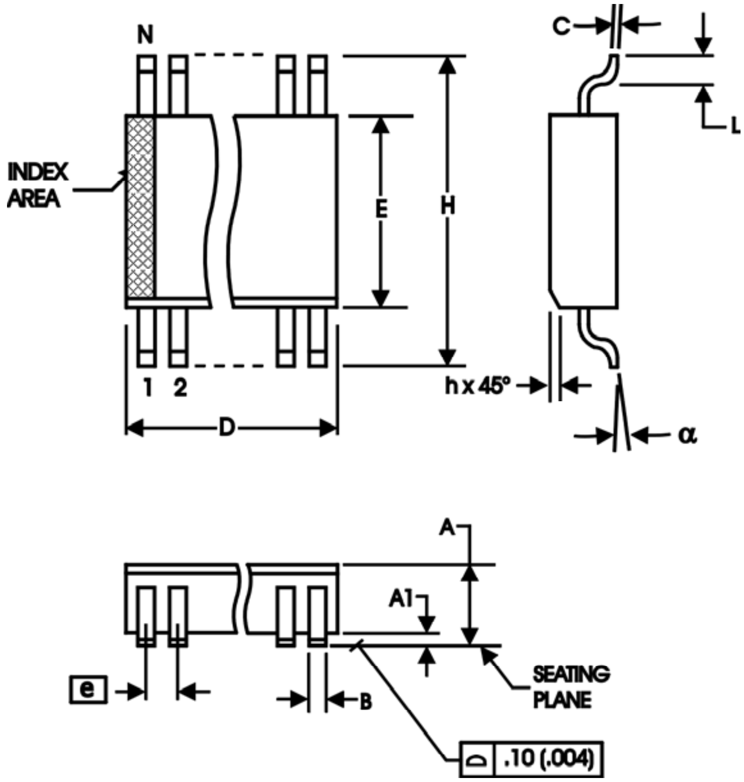


TABLE 7. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MINIMUN	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012

TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS853011BM	853011B	8 lead SOIC	96 per tube	-40°C to 85°C
ICS853011BMT	853011B	8 lead SOIC on Tape and Reel	2500	-40°C to 85°C
ICS853011BMLF	3011BLF	"Lead Free" 8 lead SOIC	96 per tube	-40°C to 85°C
ICS853011BMLFT	3011BLF	"Lead Free" 8 lead SOIC on Tape and Reel	2500	-40°C to 85°C

REVISION HISTORY SHEET				
Rev	**Table**	**Page**	**Description of Change**	**Date**
B	T3B	3	3.3V LVPECL Table - changed V_{OH} @ 85° , from 2.295V min. to 2.22V min. and 2.33V typical to 2.295V typical.	9/2/03
	T3C	4	2.5V LVPECL Table - changed V_{OH} @ 85°, from 1.495V min. to 1.42V min. and 1.53V typical to 1.495V typical.	
	T3D	4	ECL Table - changed VOH @ 85°, from -1.005V min. to -1.08V min. and --0.97V typical to -1.005V typical.	
		6	Updated LVPECL Output Termination Diagrams.	
		8	Updated LVPECL Clock Input Inteface Figure 4D.	
B		8	Corrected Figure 4C.	11/12/03
		13	Added "Lead Free" Part/Order Number rows.	
C	T4	4	AC Characteristics Table - added Additive Phase Jitter.	9/7/04
		5	Added Additive Phase Jitter Section.	